

EPIC Online Technology Meeting on Hybrid Photonics Integration, September 18th, 2023

GLOBAL CHALLENGES REQUIRE NEW TECHNOLOGIES



TELECOMMUNICATIONS





LIGHT instead of electrons

PHOTONIC INTEGRATED CIRCUIT

Integrating multiple components

on a SINGLE CHIP



MANY PARALLELS WITH ELECTRONICS



Same equipment

Similar economies of scale and cost-down

Similar margins for tech leader with volume



SIMPLIFYING COMPLEXITY: PDK

PROCESS DESIGN KIT (PDK) TOOLBOX Process know-how and building block performance













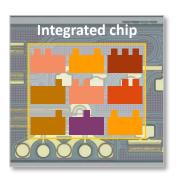
PHASE MODULATORS



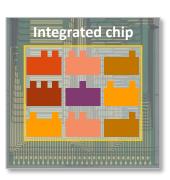


PHOTODIODE ARRAYS

DATACOM CHIPS



SENSING CHIPS







10+
Years of refining PDK



Issued and pending patent families

PDKS HELP OUR CUSTOMERS:

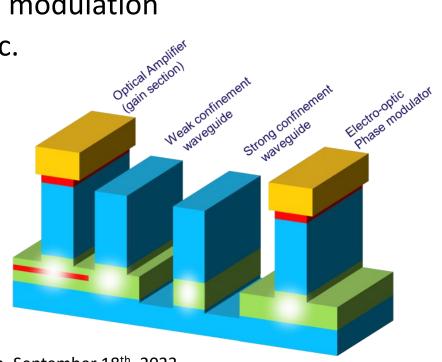
- Customise designs
- Leverage experience
- Reduce time to market
- Leverage infrastructure



indium phosphid

InP IS KEY TO SUCCESS!

- Only material suited for lasers and amplifiers
- Butt-joint integration: no compromise between active and passive components
 - Actives: lasers, amplifiers
 - Modulators: high speed phase and amplitude modulation
 - Passives: connecting waveguides, splitters, etc.
- Full on-wafer electrical testing
- Enabler for low-cost integrated circuits!



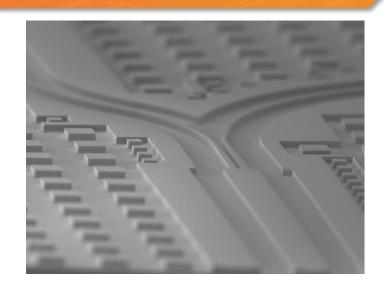


INTRODUCTION SMART PHOTONICS

InP PIC Production Line and PDK







- EU based foundry
- Open Foundry manufacturing services for InP wafers based on customers' designs
- Processes and capacity for supporting customers from prototype to volume









MULTIPLE PLATFORMS WITH DIFFERENT STRENGTHS TRANSFER PRINTING: COMBINING BEST OF ALL PLATFORMS

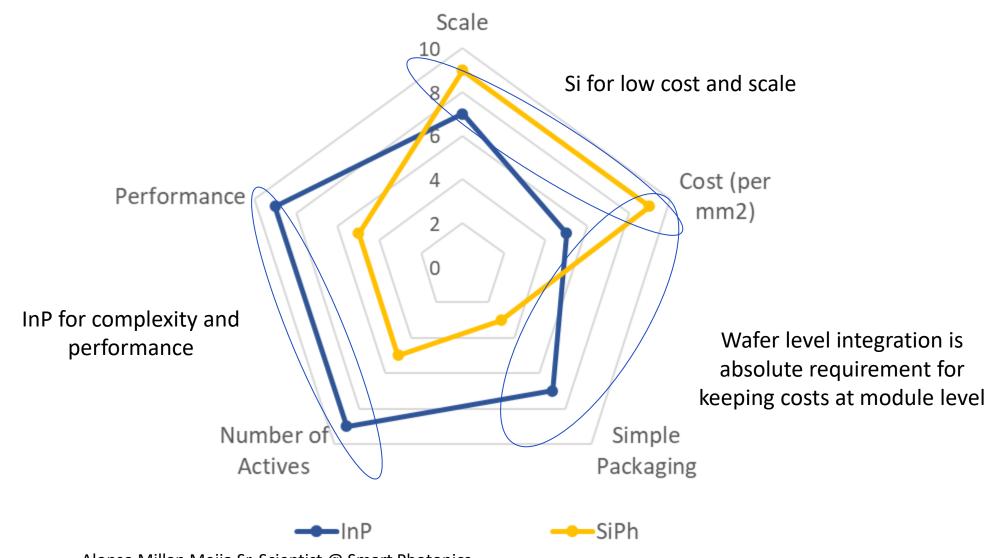
PIC platform attributes	Indium phosphide	Silicon Nitride	Silicon (CMOS) photonics	INSPIRE
Light sources and amplifiers	YYY	X	X	///
Electrical energy efficiency	~ ~	X	* * *	/ /
Electro-optic speed	~ ~	X	* * *	///
Optical connect efficiency	✓	///	✓	///
Optical signal integrity	~ ~	**	✓	///
Production scalability	✓	*	VVV	**
Active device scaling	✓	X	X	**
Passive device scaling	~	>	***	**
Hosting exotic materials	✓	***	X	/ / / /
Route to 3D integration	✓	**	///	YYY



Table 1.1: Attributes of established PIC platforms and the INSPIRE III-V/SiN platform. Red crosses X indicate a platform deficiency, and single yellow ticks \checkmark indicate a credible path is an active area of PIC development. Multiple green ticks \checkmark \checkmark indicate superior performance.

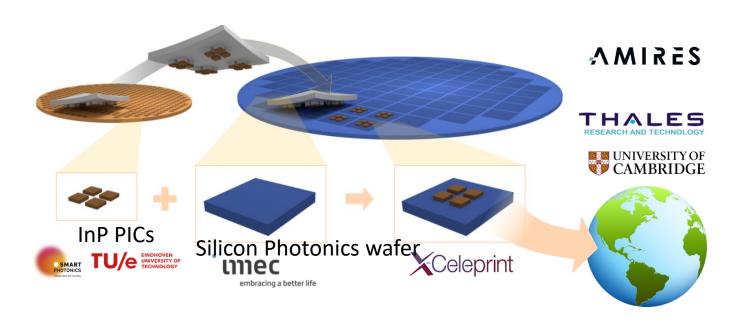


COMPLIMENTARY PERFORMANCE





INSPIRE: TECHNOLOGY DEVELOPMENT AMBROSIA: UTILISE AND VALIDATE OUR TECHNOLOGICAL ADVANCEMENT











NEXT STEP: PHOTONIXFAB

- Full EU-based photonics device value chain
- Industrial manufacturing capabilities
- Path to high-volume manufacturing





photonixFAB

WHAT DO WE NEED FROM THE COMMUNITY?

Applications! – Bring your ideas and convert them into products. Close communication is needed to bring new technologies to the market

We provide the platform; you deliver the applications.

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CONCLUSIONS



Integrated photonics: helps solving major worldwide challenges in large and high-growth markets



The industry has many parallels with electronics and is moving towards a horizontal value chain



Higher application demands drives need for platform integration



Adoption of new integration platforms needs close interaction in the photonics ecosystem



InP based devices play a key role in integrated photonics value chain



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